

EMI SHIELDING METHOD OF SEMICONDUCTOR PACKAGES

ABSTRACT

5 Disclosed is an EMI shielding method of semiconductor packages, including a tape attaching step of attaching an edge of a tape to a lower side of a frame to dispose the tape inside an inner circumferential side of the frame, a tape cutting step of forming holes through the tape at regular
10 intervals, a semiconductor package fastening step of disposing edges of lower sides of the semiconductor packages on an upper side of the tape so that bumps, formed on the lower sides of the semiconductor packages, are inserted into the holes in the tape to thus fasten the semiconductor packages at regular
15 intervals to the upper side of the tape, and a coating step of performing a coating operation over the tape to form a coat on the semiconductor packages and the upper side of the tape.

Fig. 1